

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: R. IKEZAWA, et al.

Application No.: 10/552,441

Filed: OCTOBER 7, 2005

For: ENCAPSULATING EPOXY RESIN MOLDING MATERIAL, AND
SEMICONDUCTOR DEVICE

Group AU: 2815

Examiner: Jasmine Jhihan B. Clark

Confirm. No.: 7255

AMENDMENT AFTER FINAL REJECTION

Mail Stop: AF – NO FEE

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

January 18, 2008

Sir:

In response to the Office Action mailed October 18, 2007, please amend the above-identified application as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.

OK to enter
nbc
2/4/08